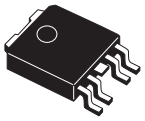
LDR1833
LDR2533

Very low drop dual voltage regulator

Features

- Output current 1 up to 500 mA
- Output current 2 up to 1.0 A
- Low dropout voltage 1 (0.3 V @ I_O = 500 mA)
- Low dropout voltage 2 (0.4 V @ I_O = 1 A)
- Very low supply current (typ. 50 µA in OFF mode, 1.6 mA max in ON mode)
- Logic-controlled electronic shutdown output voltage availability for each regulator: 1.8 V, 2.5 V, 3.3 V
- Internal current and thermal limit
- Stable with low value (min. 4.7 µF) and low ESR output capacitors
- Supply voltage rejection: 70 dB (typ.)
- Temperature range (- 40 °C to 125 °C)



PPAK

Description

The LDR1833, LDR2533 is a very low drop dual voltage regulator available in PPAK. The very low drop-voltage (0.5 V) and the very low supply current make it particularly suitable for low noise and low power applications such as PDA, Microdrive and other data storage applications while the used high voltage technology makes this device suitable for consumer applications such as Monitors and Set-top-box. For each V_O a shutdown logic control function is available (TTL compatible) to decrease the total power consumption.

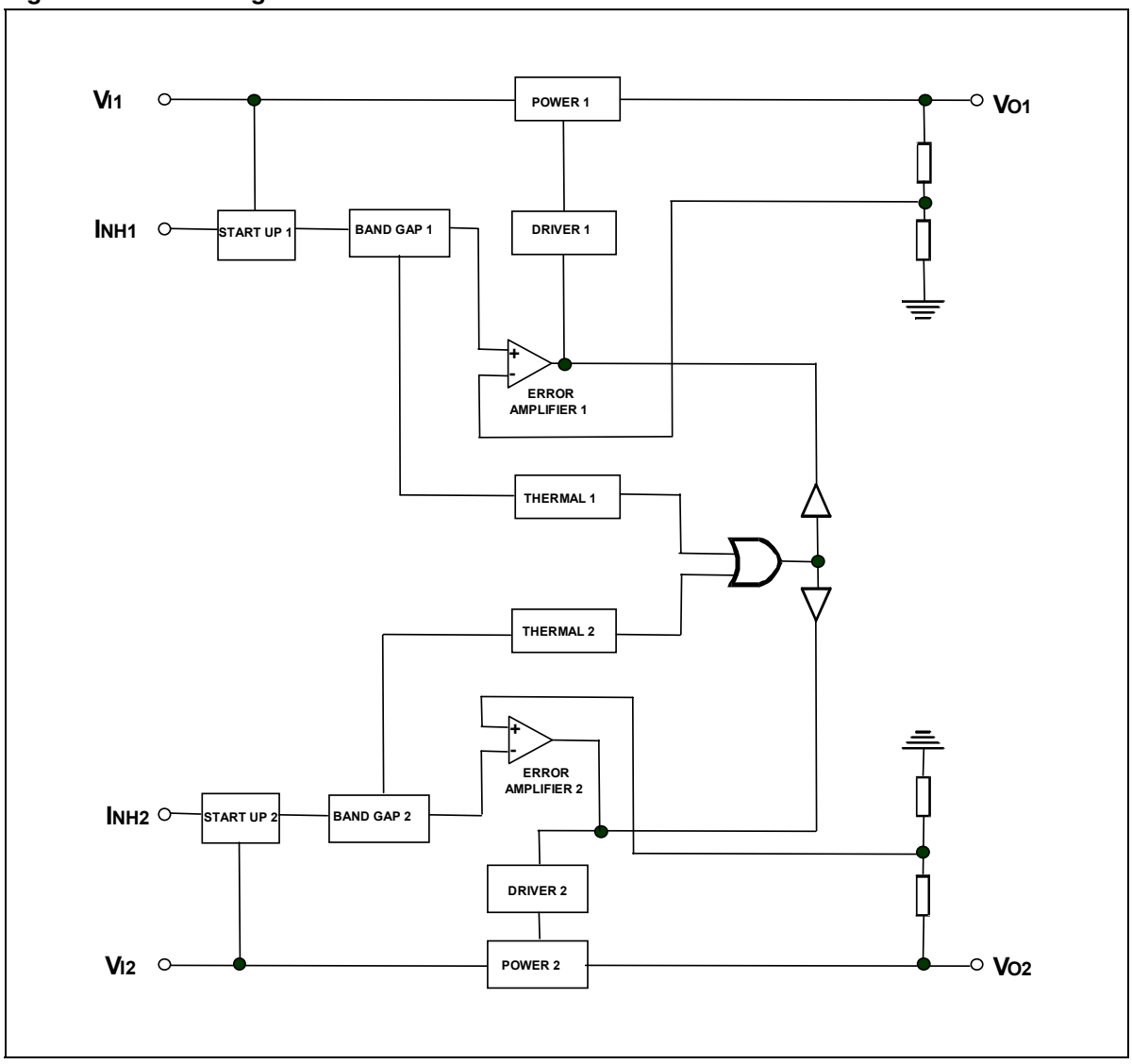
Table 1. Device summary

Order codes	Output voltages	
	V_{O1}	V_{O2}
LDR1833PT-R	1.8 V	3.3 V
LDR2533PT-R	2.5 V	3.3 V

Contents

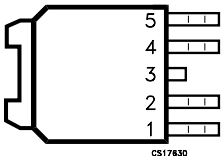
1 Diagram

Figure 1. Block diagram



2 Pin configuration

Figure 2. Pin connections (top view)



PPAK

Table 2. Pin description

Pin n°	Symbol	Name and function
3	GND	Ground pin
2	V_{I1}	Input 1 supply pin. Bypass with a 2.2µF capacitor to GND
1	V_{I2}	Input 2 supply pin. Bypass with a 2.2µF capacitor to GND
4	V_{O1}	Output 1 pin. Bypass with a 4.7µF capacitor to GND port
5	V_{O2}	Output 2 pin. Bypass with a 4.7µF capacitor to GND port

3 Maximum ratings

Table 3. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{I1} & V_{I2}	DC input voltage	-0.3 to 15	V
INH	Shutdown voltage	-0.3 to 15	V
I_O	Output current	Internally limited	
P_D	Power dissipation	Internally limited	
T_{STG}	Storage temperature range	-50 to +150	°C
T_A	Operating ambient temperature range	-40 to +125	°C

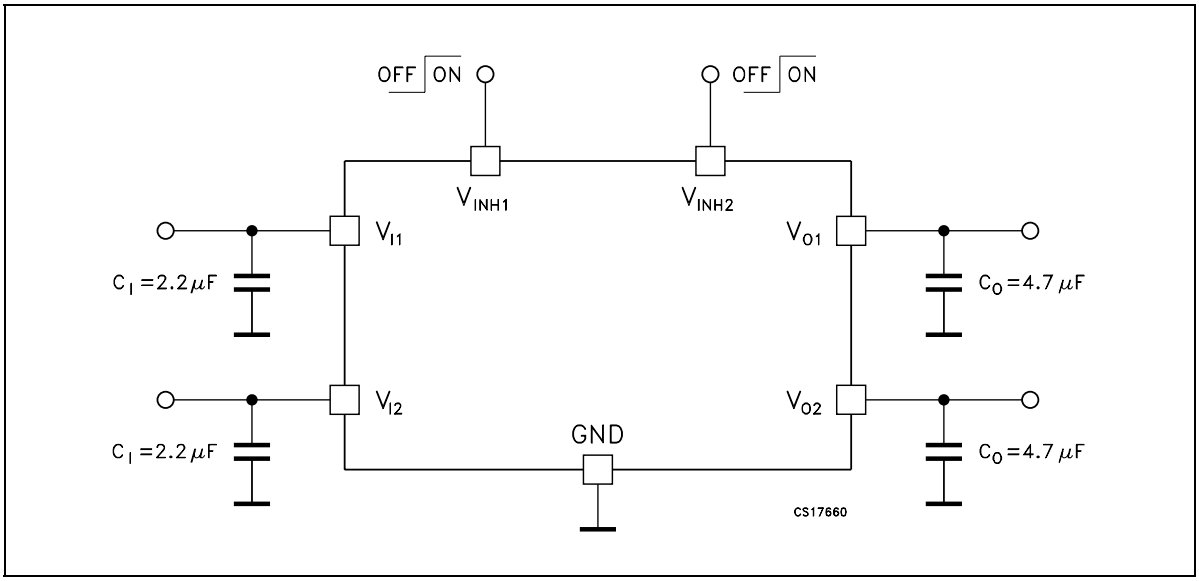
Note: Absolute maximum ratings are those values beyond which damage to the device may occur. Functional operation under these condition is not implied.

Table 4. Thermal data

Symbol	Parameter	PPAK	Unit
R_{thJC}	Thermal resistance junction-case	8	°C/W

4 Typical application

Figure 3. Typical application circuit



5 Electrical characteristics

Table 5. Electrical characteristics ($V_{I1} = V_{O1} + 2$ V, $V_{I2} = V_{O2} + 2$ V, $V_{INH1} = V_{INH2} = 2.5$ V, $C_{I1,2} = 2.2$ µF, $C_{O1,2} = 4.7$ µF, $I_{O1} = I_{O2} = 10$ mA, $T_A = -40$ °C to 125 °C, unless otherwise specified. Typical values are referred at $T_A = 25$ °C)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{O1}	Output voltage 1		-5	V_{NOM1}	+5	%V
V_{O2}	Output voltage 2		-5	V_{NOM2}	+5	%V
V_{DROP1}	Dropout voltage 1 (1)	I_{O1} = 500mA		0.3	0.7	V
V_{DROP2}	Dropout voltage 2 (1)	I_{O2} = 1A		0.4	0.8	V
ΔV_{O1}	Line regulation 1	$V_{I1} = V_{O1}$+2V to V_{O1}+7V, I_O = 250mA		15	30	mV
ΔV_{O2}	Line regulation 2	$V_{I2} = V_{O2}$+2V to V_{O2}+7V, I_O = 500mA		15	40	mV
ΔV_{O1}	Load regulation 1	$V_{I1} = V_{O1}$+2V, I_{O1} = 10 to 500mA		10		mV
ΔV_{O2}	Load regulation 2	$V_{I2} = V_{O2}$+2V, I_{O2} = 10mA to 1A		60		mV
I_{STOT}	Total supply current	$I_{O1} = I_{O2}$ = NO LOAD		2		mA
I_S	1 channel supply current	NO LOAD		1		mA
I_{QMAX}	Quiescent current	I_{O1} = 500mA, I_{O2} = 1A		30		mA
I_{SC1}	Short circuit current 1	T_A = 25°	500	800		mA
I_{SC2}	Short circuit current 2	T_A = 25°	1	1.6		A
V_{INH-H}	Enable voltage HIGH		2.4			V
V_{INH-L}	Enable voltage LOW				0.8	V
I_{INH}	Enable pin current	V_{INH} = 5V		6		µA
SVR	Supply voltage rejection (2)	$V_{I1,2} = V_{O1,2}$ +3V ±1V, $I_{O1,2}$ = 10 mA, f = 120Hz		70		dB
e_N	RMS output noise (2)	Bandwidth of 10Hz to 100kHz		0.003		$\%V_O$

1. This test is not performed for $V_O < 2.5$ V.
2. Guaranteed by design, but not tested in production

6 Typical characteristics

(unless otherwise specified T_J = 25 °C)

Figure 4. Dropout voltage (V_{O1}) vs temperature

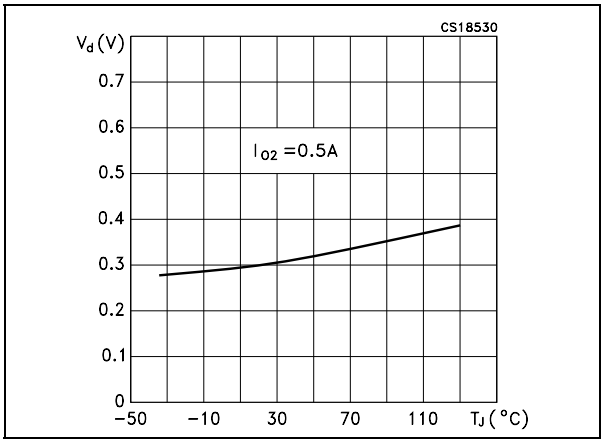


Figure 5. Dropout voltage (V_{O2}) vs temperature

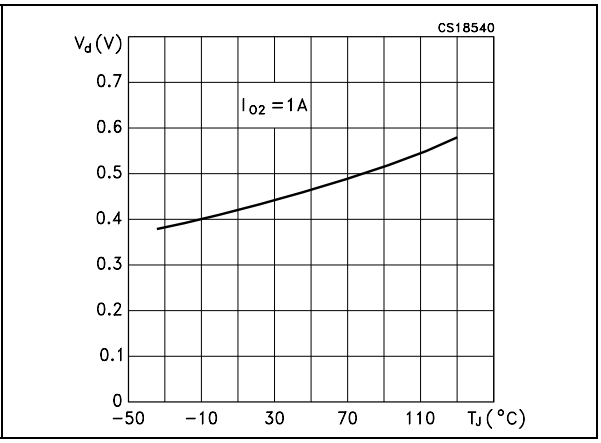


Figure 6. Dropout voltage (V_{O1}) vs temperature

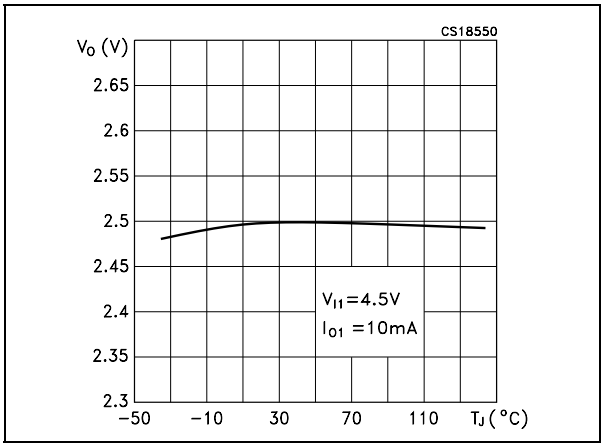


Figure 7. Dropout voltage (V_{O2}) vs temperature

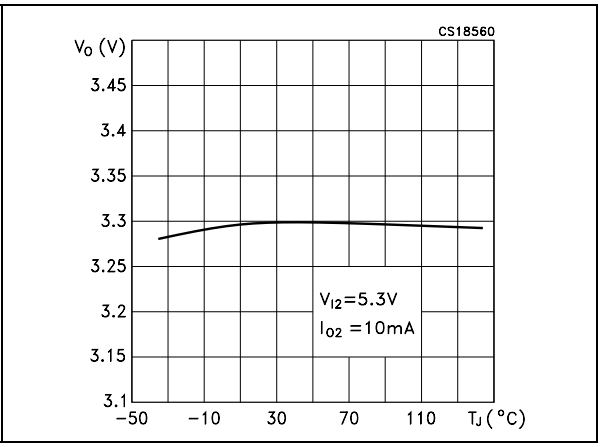


Figure 8. Line regulation (V_{O1}) vs temp.

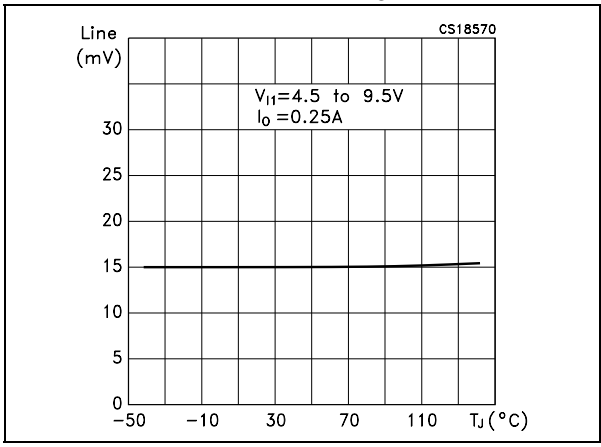


Figure 9. Load regulation (V_{O1}) vs temp.

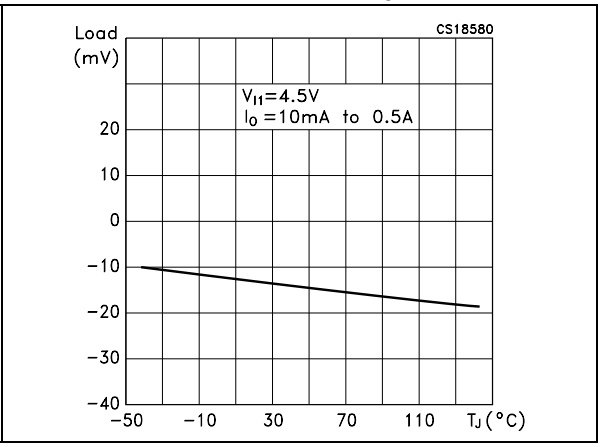


Figure 10. Line regulation (V_{O2}) vs temperature

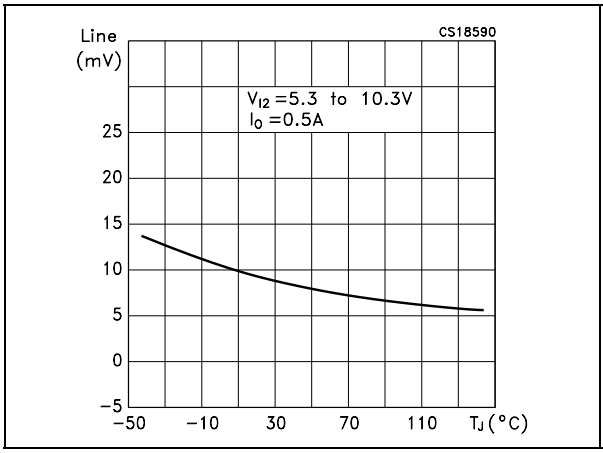


Figure 11. Load regulation (V_{O2}) vs temperature

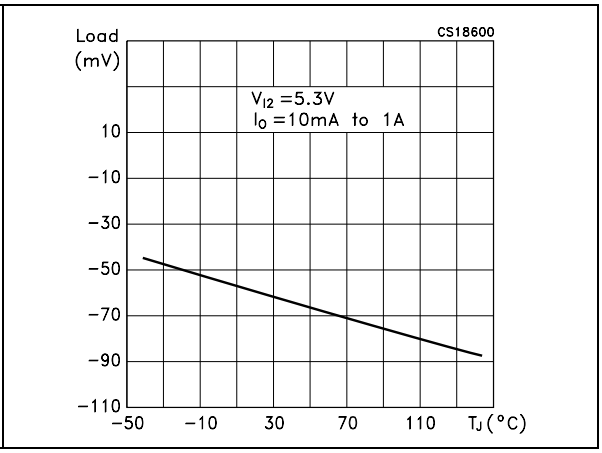


Figure 12. Short circuit current (V_{O1}) vs drop voltage

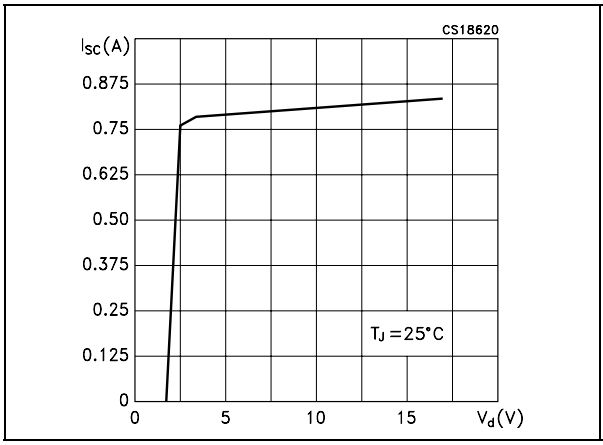


Figure 13. Short circuit current (V_{O2}) vs drop voltage

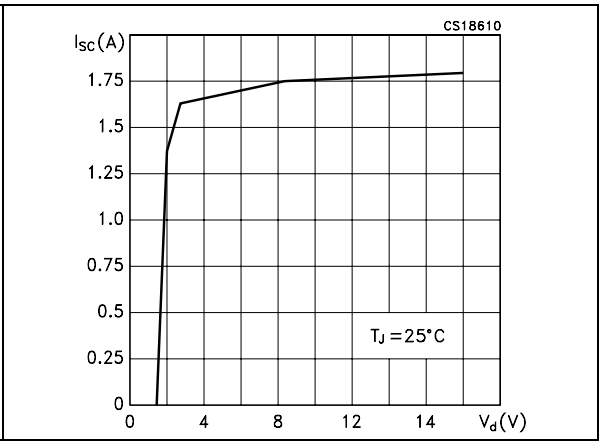


Figure 14. Inhibit voltage vs temperature

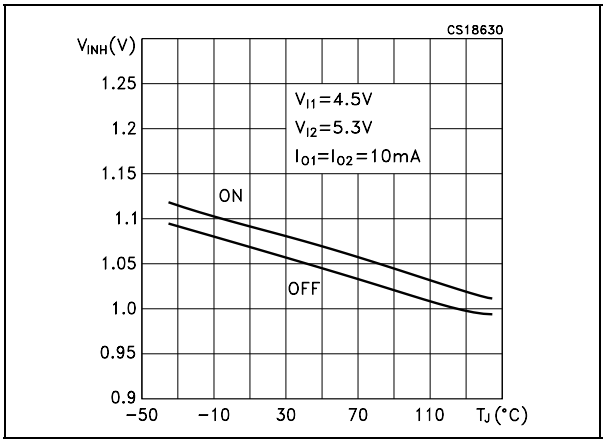


Figure 15. One channel inhibit current vs temperature

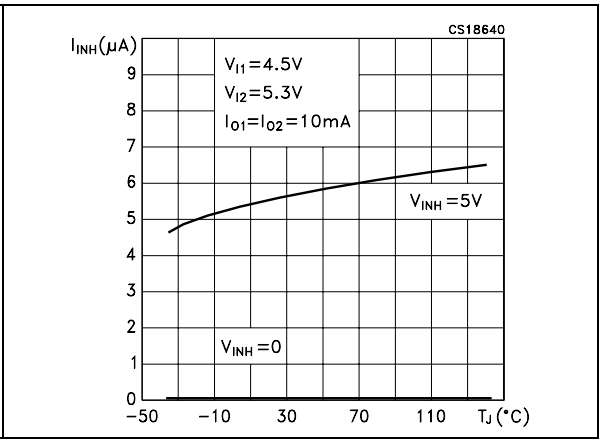


Figure 16. Supply voltage rejection vs (V_{O1}) temperature

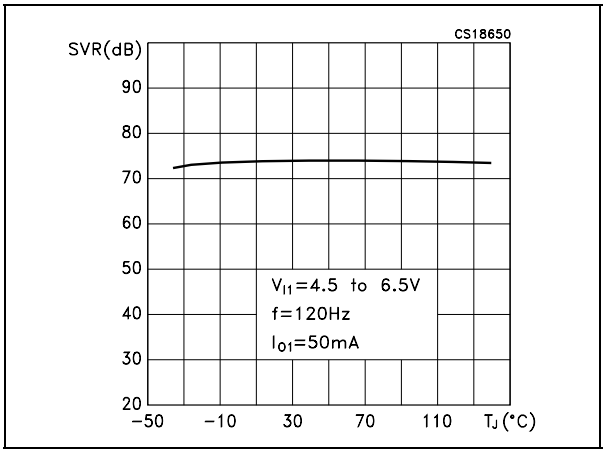


Figure 17. Supply voltage rejection vs (V_{O2}) temperature

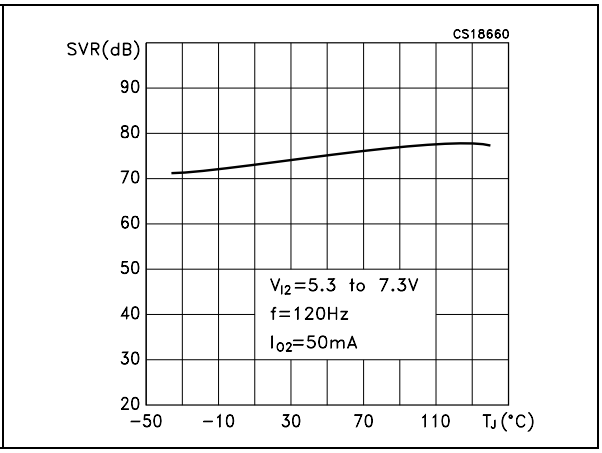


Figure 18. Supply voltage rejection (V_{O1}) vs frequency

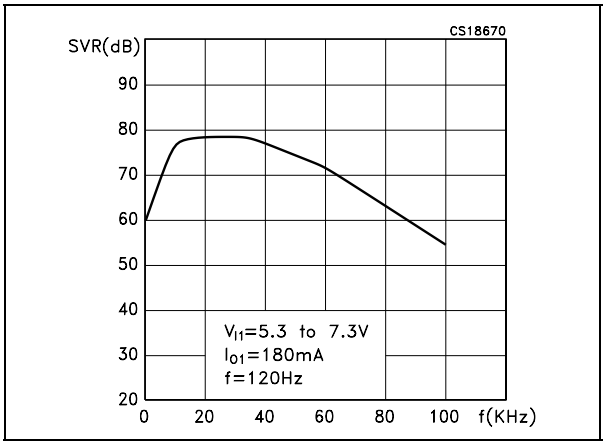


Figure 19. Supply voltage rejection (V_{O2}) vs frequency

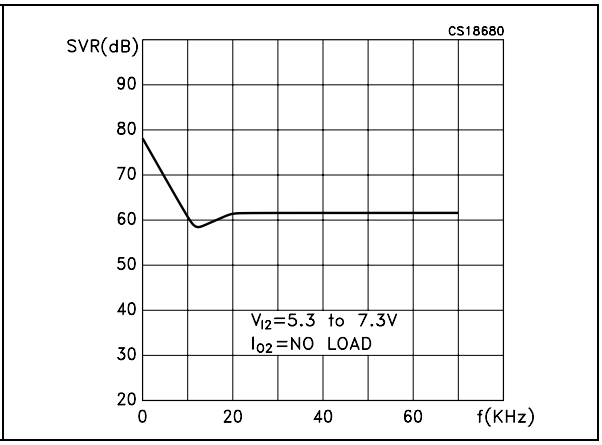


Figure 20. Maximum total quiescent current vs temperature

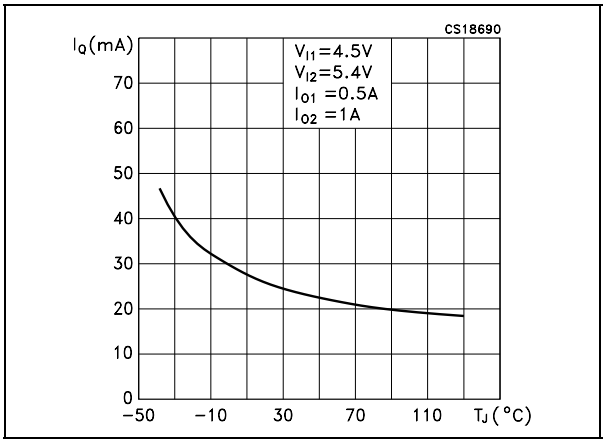


Figure 21. Total supply current vs temperature

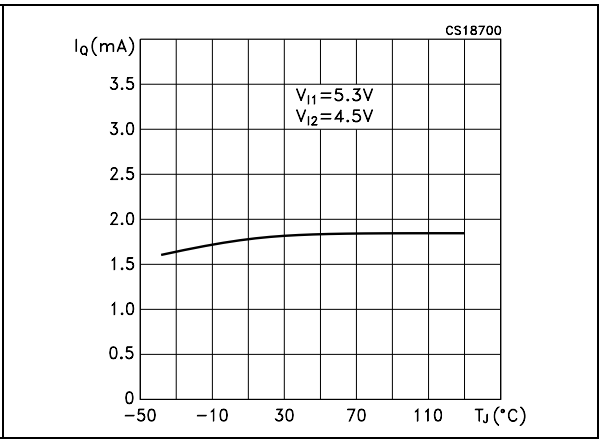


Figure 22. Quiescent current (V_{O1}) vs output current

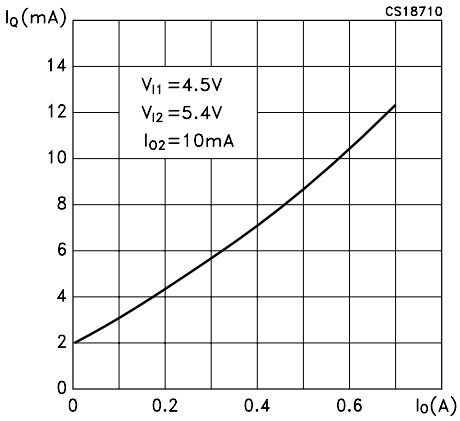


Figure 23. Quiescent current (V_{O2}) vs output current

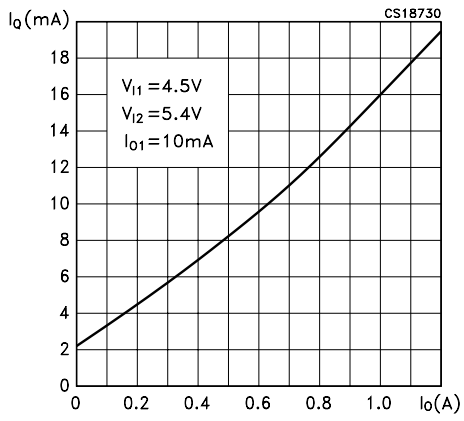


Figure 24. Thermal protection vs V_{O1}

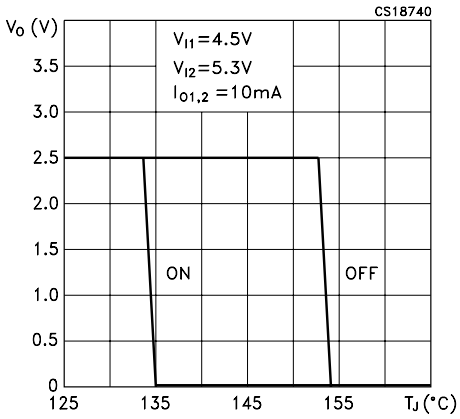
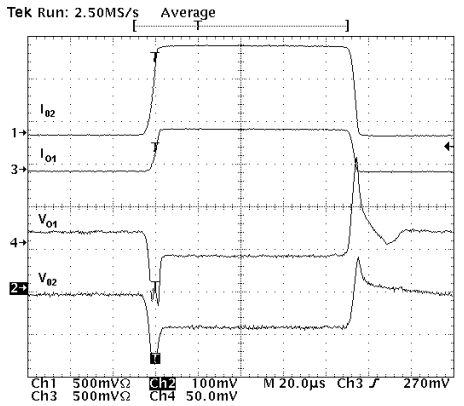
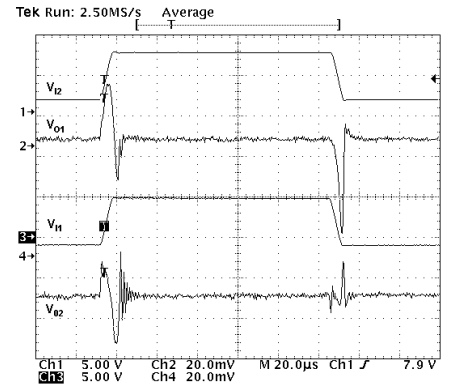


Figure 25. Load transient



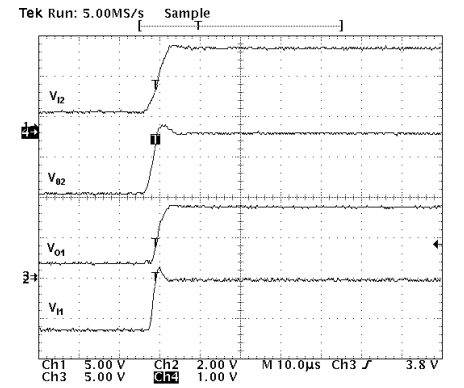
$C_{I1,2}$=1µF, $C_{O1,2}$=2.2µF, $V_{INH1,2}$=2.5V, V_{I1}=4.5V, V_{I2}=5.3V, I_{O1}=5mA to 0.5A, I_{O2}=5mA to 1A, t_{RISE}=t_{FALL}=4.2µs

Figure 26. Line transient $V_{O1,2}$



$C_{I1,2}$=0, $C_{O1,2}$=2.2µF, V_{I1}=4.4 to 10.4V, V_{I2}=5.3 to 11.3V, I_{O1}=0.25A, I_{O2}=0.5A, t_{RISE}=t_{FALL}=4.4µs

Figure 27. Start up transient V_{O1}



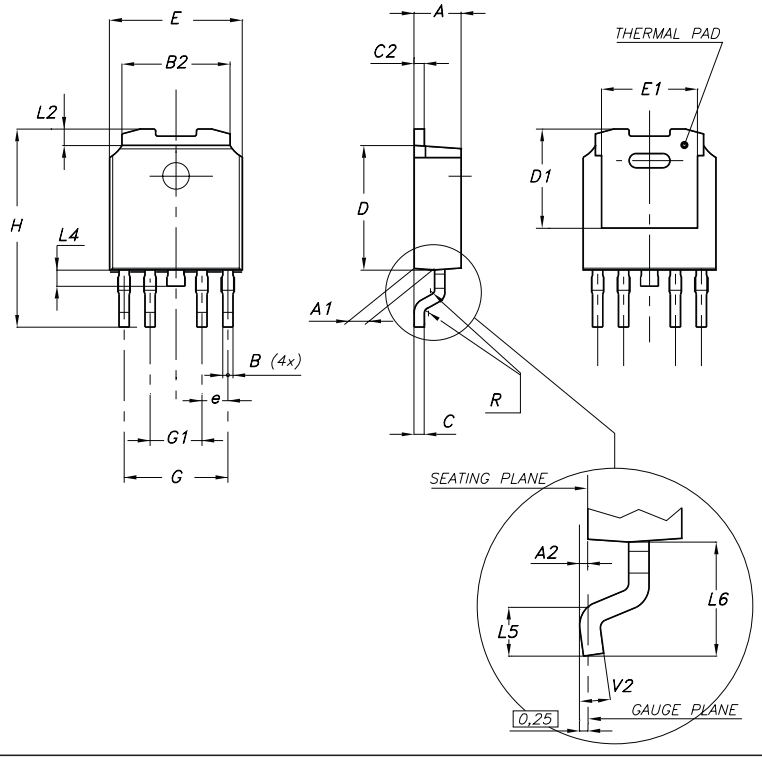
V_{I1}=1.1 to 8.5V, V_{I2}=1.2 to 9.8V, I_{O1}=0.25A, I_{O2}=0.5A, t_{RISE}=5µs

7 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second Level Interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

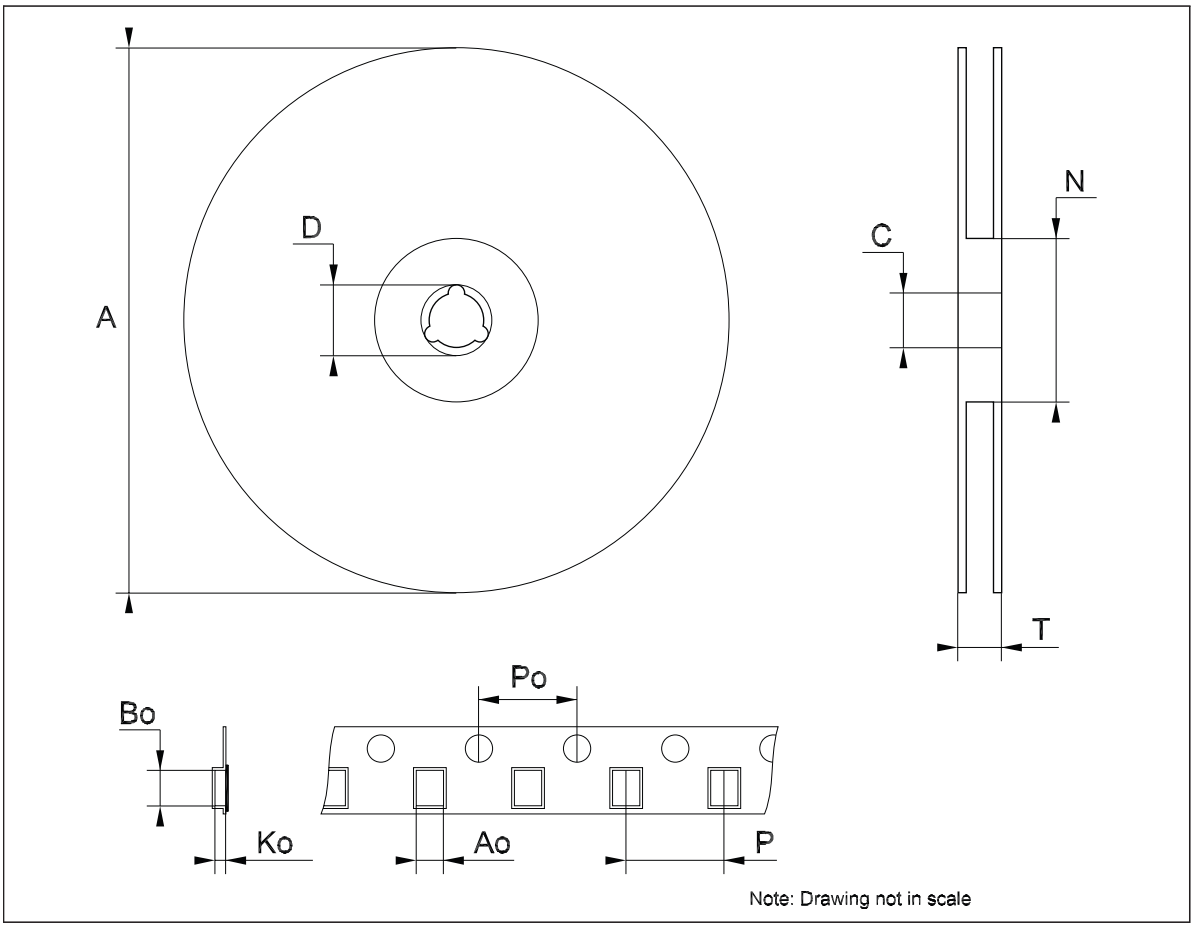
PPAK mechanical data

Dim.	mm.			inch.		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.2		2.4	0.086		0.094
A1	0.9		1.1	0.035		0.043
A2	0.03		0.23	0.001		0.009
B	0.4		0.6	0.015		0.023
B2	5.2		5.4	0.204		0.212
C	0.45		0.6	0.017		0.023
C2	0.48		0.6	0.019		0.023
D	6		6.2	0.236		0.244
D1		5.1			0.201	
E	6.4		6.6	0.252		0.260
E1		4.7			0.185	
e		1.27			0.050	
G	4.9		5.25	0.193		0.206
G1	2.38		2.7	0.093		0.106
H	9.35		10.1	0.368		0.397
L2		0.8	1		0.031	0.039
L4	0.6		1	0.023		0.039
L5	1			0.039		
L6		2.8			0.110	



Tape & reel DPAK-PPAK mechanical data

Dim.	mm.			inch.		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			330			12.992
C	12.8	13.0	13.2	0.504	0.512	0.519
D	20.2			0.795		
N	60			2.362		
T			22.4			0.882
Ao	6.80	6.90	7.00	0.268	0.272	0.2.76
Bo	10.40	10.50	10.60	0.409	0.413	0.417
Ko	2.55	2.65	2.75	0.100	0.104	0.105
Po	3.9	4.0	4.1	0.153	0.157	0.161
P	7.9	8.0	8.1	0.311	0.315	0.319



8 Revision history

Table 6. Document revision history

Date	Revision	Changes
03-Aug-2004	2	Modified: tables 1, 3, 5 and figures 3, 6, 10, 11, 14, 17, 22, 23.
15-Apr-2008	3	Modified: *Table 1 on page 1*.

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